TABLE 1. FINISH

<table>
<thead>
<tr>
<th>PART NO.</th>
<th>PART NAME</th>
<th>TERMINAL AREA / LOCK HINGE AREA</th>
<th>CONTACT AREA</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>CONTACT</td>
<td>Au FLASH OVER Ni (3 μm MIN.)</td>
<td>Au (10.5 μm MIN.) OVER Ni (2~6 μm)</td>
</tr>
<tr>
<td>2</td>
<td>BODY</td>
<td></td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>BODY</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

NOTES:
1. COPLANARITY 0.08mm max.
2. LOT INFORMATION IS SHOWN AS BELOW.

PRODUCTION LINE NO.

PRODUCTION DATE (YMDD)

2014/09/16

All the pattern and Via holes under the connector should be coated by resist.

APPLICABLE PWB. DIMENSION FOR PAD LAYOUT (REF.)

APPLICABLE PWB. DIMENSION FOR RESTRICTED AND INSULATION AREA (REF.)

OUTLINE OF CONNECTOR

RESTRICTED AREA (No pattern and Via hole)

Recommended phone case location area behind the cover to keep cover fully open.

NOTE:

- CL: Copper Foil
- M: Stainless
- S: Stainless (Mild Steel)
- G: Glass
- A: Aluminum
- L: Copper Alloy
- C: Copper
- N: Nickel
- Au: Gold
- Ni: Nickel
- Cu: Copper